

IN THE CLAIMS:

Claims 1 through 6 have been amended herein. All of the pending claims 1 through 6 are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

Listing of Claims:

1. (Currently Amended) A method of enhancing adhesion of a compound to a surface of a substrate comprising:
supplying an automolding system having providing a semiconductor substrate having the surface located therein;
finding irregularities to remove from the semiconductor substrate by scanning the semiconductor substrate to locate irregularities while the semiconductor substrate is located in the automolding system; and
roughening the surface of the semiconductor substrate when removing irregularities when the semiconductor substrate is located in the automolding system.
2. (Currently Amended) The method according to claim 1, wherein roughening comprises removing contamination and foreign particles from the surface of the semiconductor substrate when the semiconductor substrate is located in the automolding system.
3. (Currently Amended) A method of enhancing adhesion of a material to a surface of a substrate comprising:
supplying an automolding system having providing a semiconductor substrate having a the surface;
determining irregularities to remove from the semiconductor substrate by scanning the semiconductor substrate when the semiconductor substrate is located in the automolding system; and
roughening the surface of the semiconductor substrate while removing irregularities when the semiconductor substrate is located in the automolding system.

4. (Currently Amended) The method according to claim 3, wherein roughening comprises removing contamination and foreign particles from the surface of the semiconductor substrate when the semiconductor substrate is located in the automolding system.

5. (Currently Amended) A method for improving adhesion of a compound to a surface of a substrate comprising:
supplying an automolding system having providing a semiconductor substrate having the surface located in the automolding system;
locating irregularities to be removed from the semiconductor substrate by scanning the semiconductor substrate when the semiconductor substrate is located in the automolding system;
and
roughening the surface of the semiconductor substrate while removing irregularities from the semiconductor substrate when the semiconductor substrate is located in the automolding system.

6. (Currently Amended) The method according to claim 5, wherein roughening comprises removing contamination and foreign particles from the surface of the semiconductor substrate when the semiconductor substrate is located in the automolding system.